

(2)

L4 ANSWER 1 OF 1 WPIX (C) 2002 THOMSON DERWENT
AN ***1998-476912*** [41] WPIX
DNC C1998-144127
TI Highly thermal conductive resin compsn. used as sealant and adhesive for
electronic parts - comprises aluminium nitride powder treated with
fluidity modifier and resin.
DC A28 A85 L03
PA (MITC) MITSUI PETROCHEM IND CO LTD
CYC 1
PI JP 10204300 A 19980804 (199841)* 7p C08L101-00
ADT JP 10204300 A JP 1997-11493 19970124
PRAI JP 1997-11493 19970124
IC ICM C08L101-00
ICS C08K003-22; C08K003-28; C08K003-36; C08K009-02; C08K009-04
AB JP 10204300 A UPAB: 19981014
Resin compsn. (I) with high thermal conductivity comprises: 100 pts.wt. (A)
resin(s); and 50-300 pts. wt. (B) aluminium nitride powder treated with
fluidity modifier to improve fluidity. Resin compsn. with high thermal
conductivity comprises: 100 pts.wt. (A) and 50-300 pts.wt. (C) waterproof
aluminium nitride powder treated with fluidity modifier to improve
fluidity is also claimed. ACN
USE - (I) and (II) are useful as material for preparation of sealant
and adhesive for electronic parts or material of laminate substrate(s),
packaging material, etc.
ADVANTAGE - (I) and (II) have uniform compsn. and good thermal
conductivity.
Dwg. 0/0
FS CPI
FA AB
MC CPI: A08-M09A; A09-A03; L03-H04E1; L04-C20A
DRN 1694-U